

Wafer Level Packaging Market Report by Packaging Technology (3D TSV WLP, 2.5D TSV WLP, WLCSP, Nano WLP, and Others), End Use Industry (Aerospace and Defense, Consumer Electronics, IT & Telecommunication, Healthcare, Automotive, and Others), and Region 2024-2032

<https://marketpublishers.com/r/W5798CAB7D5DEN.html>

Date: April 2024

Pages: 141

Price: US\$ 3,899.00 (Single User License)

ID: W5798CAB7D5DEN

Abstracts

The global wafer level packaging market size reached US\$ 5.7 Billion in 2023. Looking forward, IMARC Group expects the market to reach US\$ 22.5 Billion by 2032, exhibiting a growth rate (CAGR) of 16.1% during 2024-2032.

The wafer-level packaging (WLP) refers to a packaging solution used for adding a protective layer of electronic connections and integrated circuits (ICs). It is used for devices, such as microphones, pressure sensors, accelerometers, gyroscopes, capacitors, resistors and transistors. Some of the commonly used WLP integration types include fan-out (FO), fan-in (FI), flip-chip, 3D FOWLP. These solutions are used at the wafer-level of the device, instead of dicing the wafer into the individual die and packaging them. This offers various benefits, such as a reduction in the size of the wafer chips, streamlining of the manufacturing processes and improvements in chip functionalities. The ultrathin wafers also provide improved heat dissipation and performance, form factor reduction and minimal power consumption.

Significant growth in the electronics industry across the globe represents one of the key factors creating a positive outlook on the market growth. Furthermore, the increasing requirement for more compact and faster consumer electronics is also driving the market growth. This has also enhanced the overall demand for cost-effective and high-performance packaging solutions for enhanced mechanical protection, structural

support and extended battery life of the devices. Additionally, various technological advancements, such as the integration of connected devices with the Internet of Things (IoT), are acting as other growth-inducing factors. For instance, WLP is widely used for the manufacturing of radar systems in self-driving automobiles. It is also used in the healthcare sector for the production of various wearable devices. Other factors, including increasing circuit miniaturization in microelectronic devices, along with extensive research and development (R&D) activities, are anticipated to drive the market further.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global wafer level packaging market report, along with forecasts at the global, regional and country level from 2024-2032. Our report has categorized the market based on packaging technology and end use industry.

Breakup by Packaging Technology:

- 3D TSV WLP
- 2.5D TSV WLP
- WLCSP
- Nano WLP
- Others

Breakup by End Use Industry:

- Aerospace and Defense
- Consumer Electronics
- IT & Telecommunication
- Healthcare
- Automotive
- Others

Breakup by Region:

- North America
- United States
- Canada
- Asia-Pacific
- China

Japan
India
South Korea
Australia
Indonesia
Others
Europe
Germany
France
United Kingdom
Italy
Spain
Russia
Others
Latin America
Brazil
Mexico
Others
Middle East and Africa

Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being Amkor Technology Inc., China Wafer Level CSP Co. Ltd., Chipbond Technology Corporation, Deca Technologies Inc. (Infineon Technologies AG), Fujitsu Limited, IQE PLC, JCET Group Co. Ltd., Siliconware Precision Industries Co. Ltd. (Advanced Semiconductor Engineering Inc.), Tokyo Electron Ltd. and Toshiba Corporation.

Key Questions Answered in This Report

1. How big is the global wafer level packaging market?
2. What is the expected growth rate of the global wafer level packaging market during 2024-2032?
3. What are the key factors driving the global wafer level packaging market?
4. What has been the impact of COVID-19 on the global wafer level packaging market?
5. What is the breakup of the global wafer level packaging market based on the packaging technology?
6. What is the breakup of the global wafer level packaging market based on the end use industry?

7. What are the key regions in the global wafer level packaging market?
8. Who are the key players/companies in the global wafer level packaging market?

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